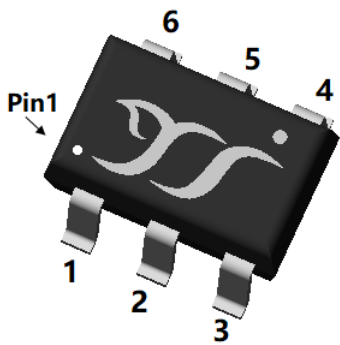
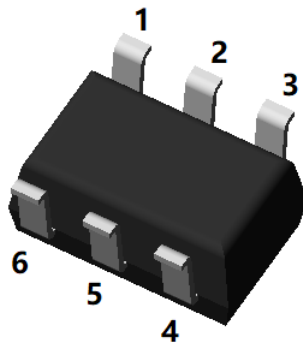


N-Channel and P-Channel Complementary MOSFET

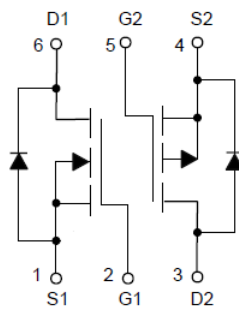


Top View



Bottom View

SOT-363



Product Summary

NMOS

- V_{DS} 60V
- I_D 0.32A
- $R_{DS(ON)}$ (at $V_{GS}=10V$) $< 1.15\Omega$
- $R_{DS(ON)}$ (at $V_{GS}=4.5V$) $< 1.35\Omega$

PMOS

- V_{DS} -60V
- I_D -0.19A
- $R_{DS(ON)}$ (at $V_{GS}=-10V$) $< 3.5\Omega$
- $R_{DS(ON)}$ (at $V_{GS}=-4.5V$) $< 4.3\Omega$

General Description

- Voltage controlled small signal switch
- Low $R_{DS(ON)}$
- Low Gate Charge
- Moisture Sensitivity Level 1
- Epoxy Meets UL 94 V-0 Flammability Rating
- Halogen Free

Applications

- Video monitor
- Power management

Limiting Values

Parameter	Conditions		Symbol	NMOS		PMOS		Unit
				Min	Max	Min	Max	
Drain-source Voltage			V_{DS}	-	60	-	-60	V
Gate-source Voltage			V_{GS}	-20	20	-20	20	V
Continuous Drain Current (Note 1,2)	Steady-State	$T_A=25^\circ C$	NMOS: $V_{GS}=10V$	-	0.32	-	-0.19	A
			PMOS: $V_{GS}=-10V$	-	0.2	-	-0.12	
		$T_A=100^\circ C$	NMOS: $V_{GS}=10V$	-	0.2	-	-0.12	
			PMOS: $V_{GS}=-10V$	-	0.1	-	0.1	
Pulsed Drain Current	$T_A=25^\circ C, t_p \leq 10\mu s$		I_{DM}	-	2	-	-1	A
Maximum Body-Diode Continuous Current	$T_A=25^\circ C$		I_S	-	0.3	-	-0.19	A
Total Power Dissipation (Note 1,2)	Steady-State	$T_A=25^\circ C$	P_D	-	0.25	-	0.25	W
		$T_A=100^\circ C$		-	0.1	-	0.1	
Junction and Storage Temperature Range			T_J, T_{STG}	-55	150	-55	150	$^\circ C$

Thermal Resistance

Parameter	Symbol	NMOS		PMOS		Units
		Typ	Max	Typ	Max	
Thermal Resistance Junction-to-Ambient (Note 2)	$R_{\theta JA}$	-	500	-	500	$^\circ C/W$

Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJL8402ADW	F2	842	3000	30000	120000	7"Reel



YJL8402ADW

■ NMOS Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A, T_j=25^\circ C$	60	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=60V, V_{GS}=0V, T_j=25^\circ C$	-	-	1	μA
		$V_{DS}=60V, V_{GS}=0V, T_j=150^\circ C$	-	-	100	
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V, T_j=25^\circ C$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A, T_j=25^\circ C$	1.1	1.6	2.1	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=0.3A, T_j=25^\circ C$	-	0.87	1.15	Ω
		$V_{GS}=4.5V, I_D=0.2A, T_j=25^\circ C$	-	1	1.35	
Diode Forward Voltage	V_{SD}	$I_S=0.3A, V_{GS}=0V, T_j=25^\circ C$	-	0.84	1.2	V
Gate Resistance	R_G	$f=1MHz, T_j=25^\circ C$	-	5.3	-	Ω
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{DS}=30V, V_{GS}=0V, f=1MHz, T_j=25^\circ C$	-	35.6	-	pF
Output Capacitance	C_{oss}		-	3.4	-	
Reverse Transfer Capacitance	C_{rss}		-	2.1	-	
Switching Parameters						
Total Gate Charge	Q_g	$V_{GS}=10V, V_{DS}=30V, I_D=0.3A, T_j=25^\circ C$	-	1.24	-	nC
Gate-Source Charge	Q_{gs}		-	0.24	-	
Gate-Drain Charge	Q_{gd}		-	0.36	-	
Reverse Recovery Charge	Q_{rr}	$I_F=0.3A, di/dt=100A/\mu s, V_{GS}=0V, V_R=30V, T_j=25^\circ C$	-	4	-	nC
Reverse Recovery Time	t_{rr}		-	10.6	-	ns
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=10V, V_{DS}=30V, I_D=0.3A, R_{GEN}=3\Omega, T_j=25^\circ C$	-	2.7	-	ns
Turn-on Rise Time	t_r		-	2.8	-	
Turn-off Delay Time	$t_{D(off)}$		-	5.4	-	
Turn-off Fall Time	t_f		-	73	-	



YJL8402ADW

PMOS Electrical Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Units
Static Parameter						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A, T_j=25^\circ C$	-60	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-60V, V_{GS}=0V, T_j=25^\circ C$	-	-	-1	μA
		$V_{DS}=-60V, V_{GS}=0V, T_j=150^\circ C$	-	-	-100	
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V, T_j=25^\circ C$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A, T_j=25^\circ C$	-0.9	-1.4	-1.9	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-0.1A, T_j=25^\circ C$	-	2.7	3.5	Ω
		$V_{GS}=-4.5V, I_D=-0.1A, T_j=25^\circ C$	-	3.2	4.3	
Diode Forward Voltage	V_{SD}	$I_S=-0.19A, V_{GS}=0V, T_j=25^\circ C$	-	-0.88	-1.2	V
Gate Resistance	R_G	$f=1MHz, T_j=25^\circ C$	-	31	-	Ω
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{DS}=-30V, V_{GS}=0V, f=1MHz, T_j=25^\circ C$	-	22.6	-	pF
Output Capacitance	C_{oss}		-	3.2	-	
Reverse Transfer Capacitance	C_{rss}		-	1.5	-	
Switching Parameters						
Total Gate Charge	Q_g	$V_{GS}=-10V, V_{DS}=-30V, I_D=-0.1A, T_j=25^\circ C$	-	2.45	-	nC
Gate-Source Charge	Q_{gs}		-	0.45	-	
Gate-Drain Charge	Q_{gd}		-	0.78	-	
Reverse Recovery Charge	Q_{rr}	$I_F=-0.1A, di/dt=100A/\mu s, V_{GS}=0V, V_R=-30V, T_j=25^\circ C$	-	2.65	-	nC
Reverse Recovery Time	t_{rr}		-	9.8	-	ns
Turn-on Delay Time	$t_{D(on)}$	$V_{GS}=-10V, V_{DS}=-30V, I_D=-0.1A, R_{GEN}=3\Omega, T_j=25^\circ C$	-	0.4	-	ns
Turn-on Rise Time	t_r		-	2.3	-	
Turn-off Delay Time	$t_{D(off)}$		-	4	-	
Turn-off Fall Time	t_f		-	60.6	-	

Note:

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- The value of $R_{\theta JA}$ is measured with the device mounted on the 40mm*40mm*1.1mm single layer FR-4 PCB board with 1 in² pad of 2oz. Copper, in the still air environment with $T_A=25^\circ C$. The maximum allowed junction temperature of 150 $^\circ C$. The value in any given application depends on the user's specific board design.



YJL8402ADW

■ NMOS Typical Electrical and Thermal Characteristics Diagrams

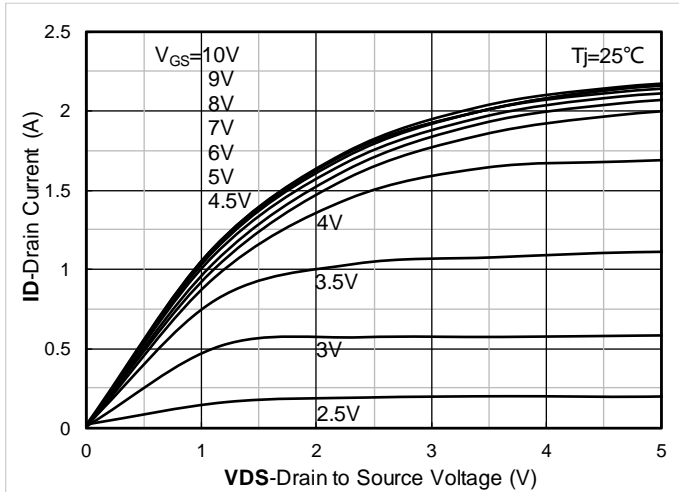


Figure 1. Output Characteristics; typical values

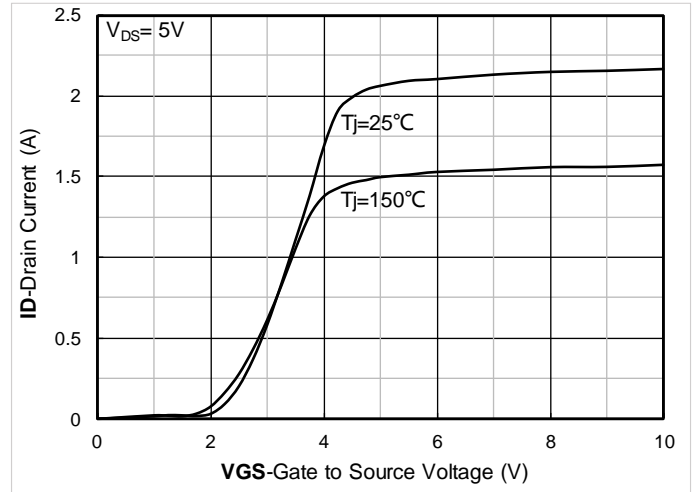


Figure 2. Transfer Characteristics; typical values

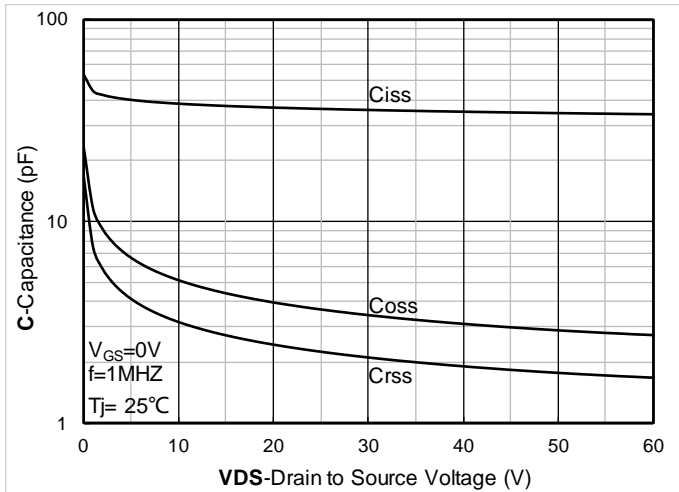


Figure 3. Capacitance Characteristics; typical values

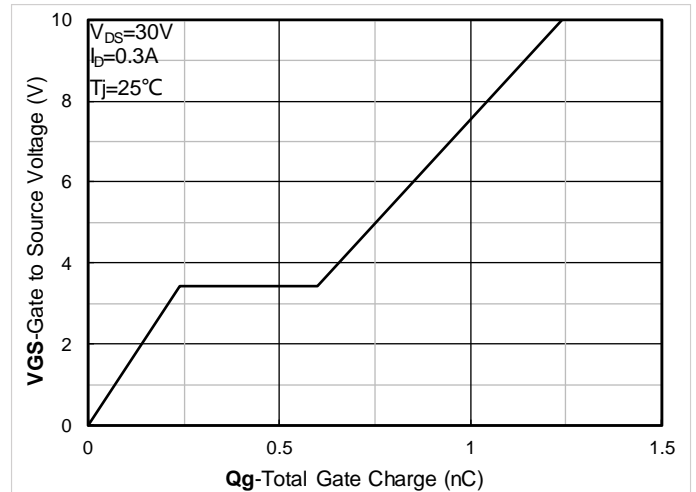


Figure 4. Gate Charge; typical values

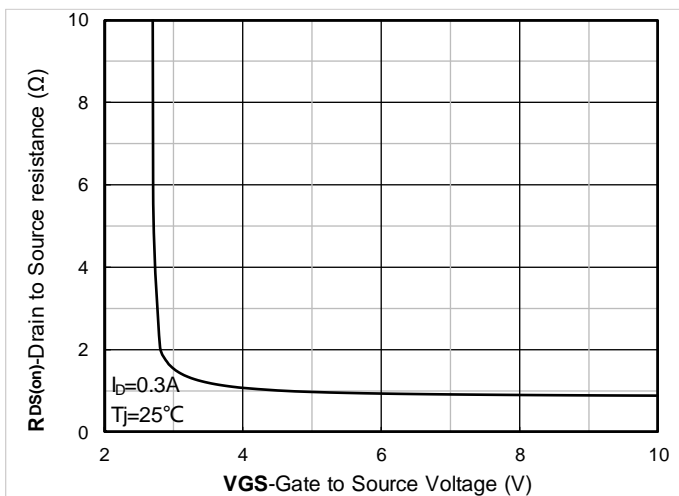


Figure 5. On-Resistance vs. Gate to Source Voltage; typical values

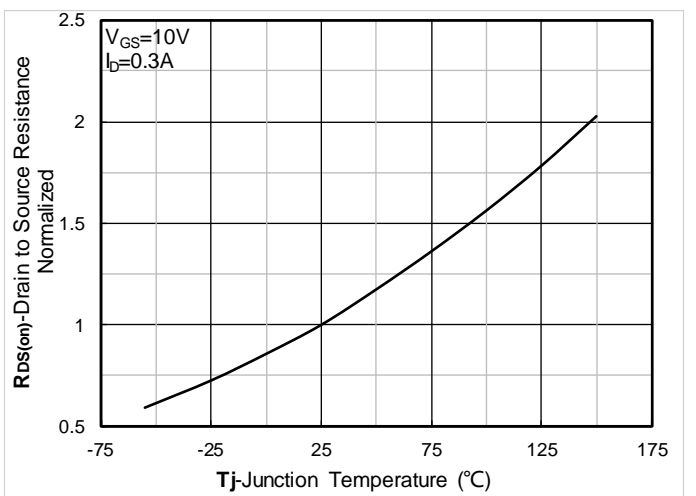


Figure 6. Normalized On-Resistance



YJL8402ADW

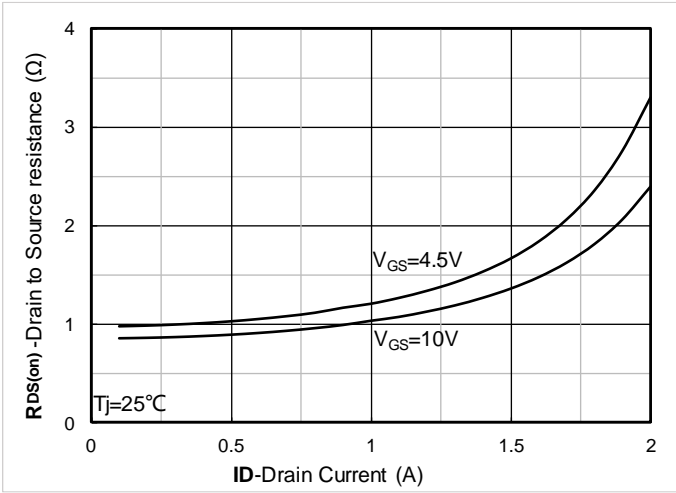


Figure 7. RDS(on) vs. Drain Current; typical values

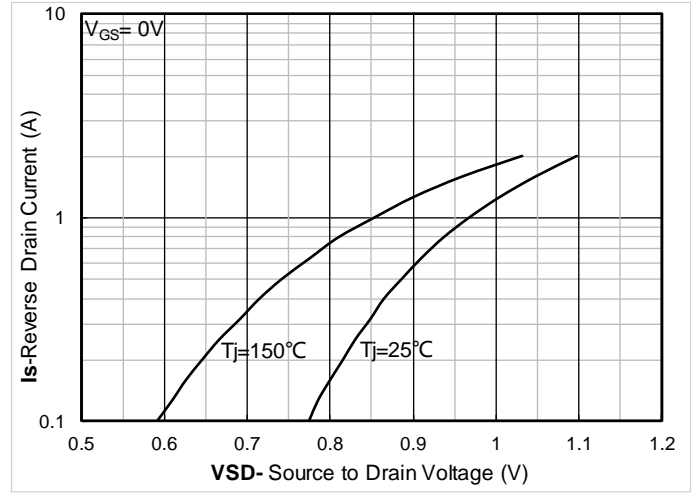


Figure 8. Forward characteristics of reverse diode; typical values

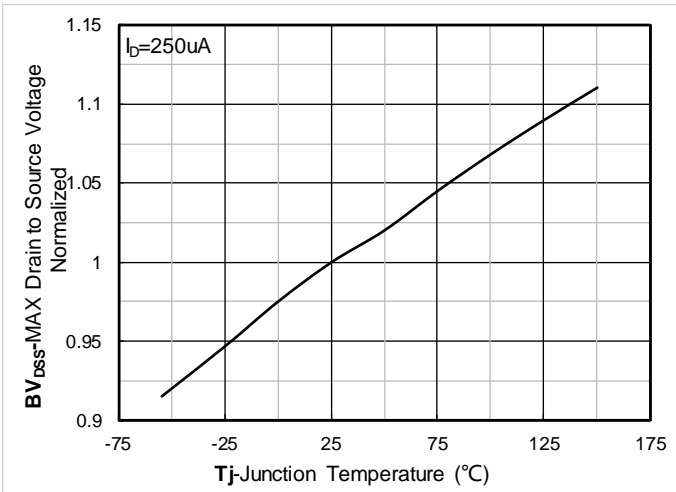


Figure 9. Normalized breakdown voltage

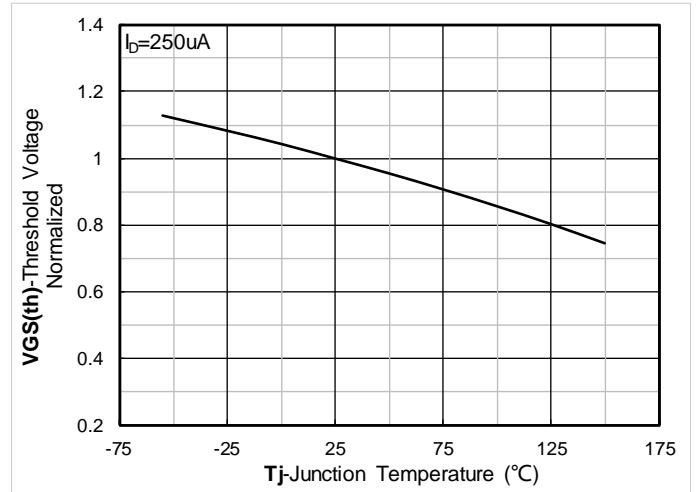


Figure 10. Normalized Threshold voltage

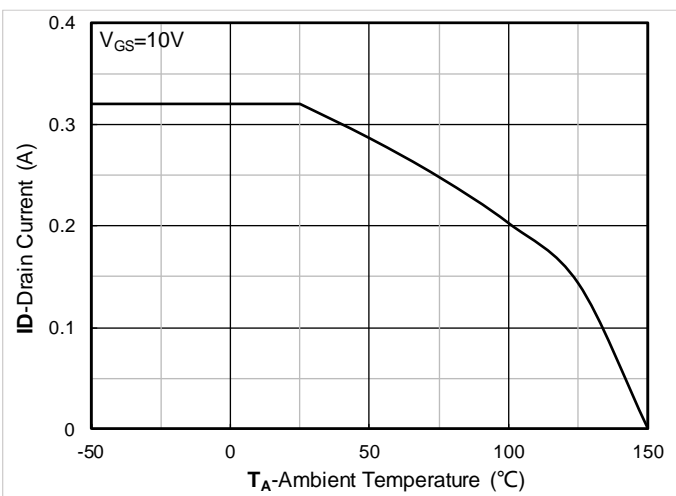


Figure 11. Current dissipation

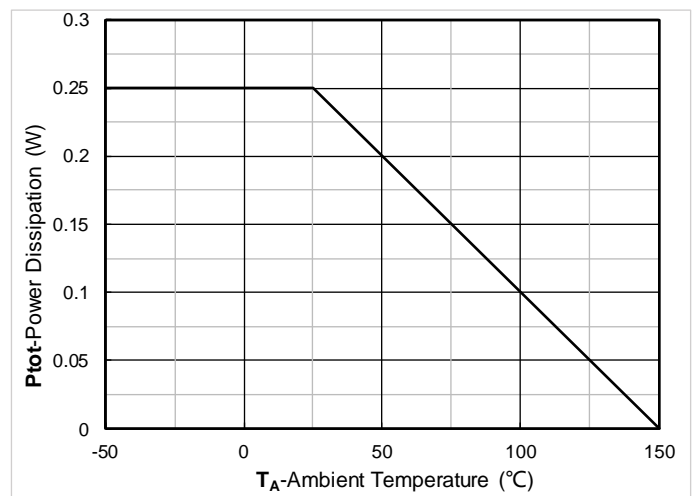


Figure 12. Power dissipation

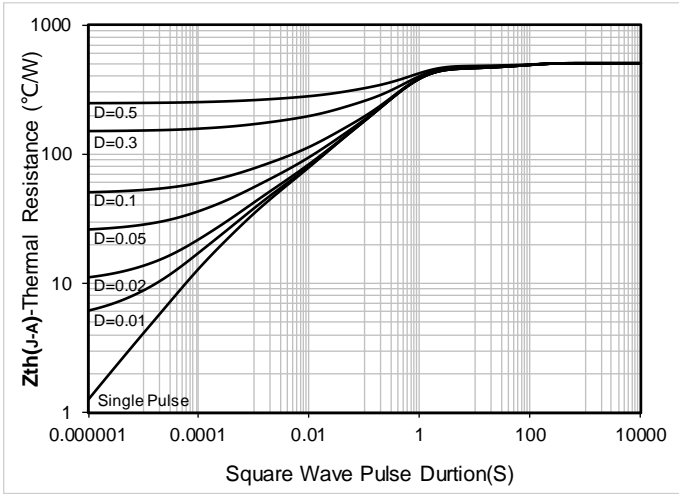


Figure 13. Maximum Transient Thermal Impedance

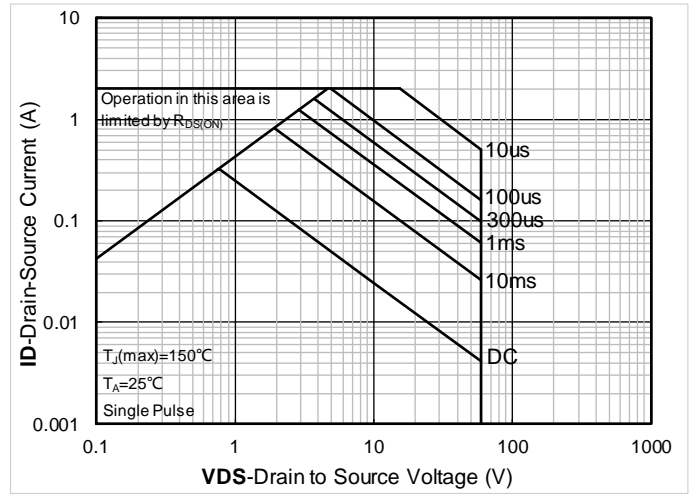


Figure 14. Safe Operation Area

PMOS Typical Electrical and Thermal Characteristics Diagrams

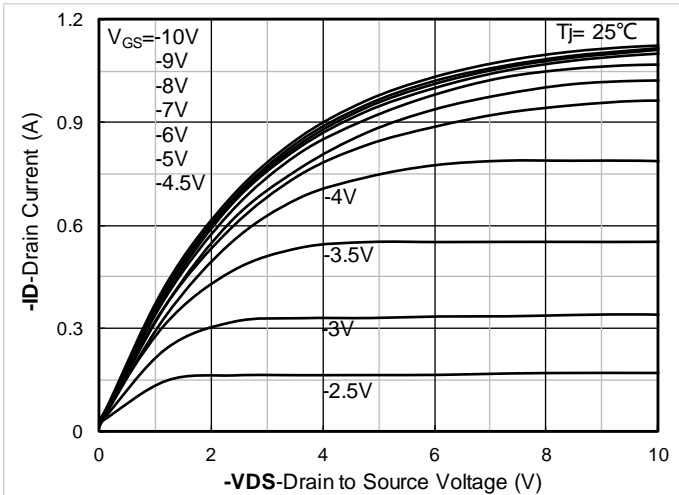


Figure 1. Output Characteristics; typical values

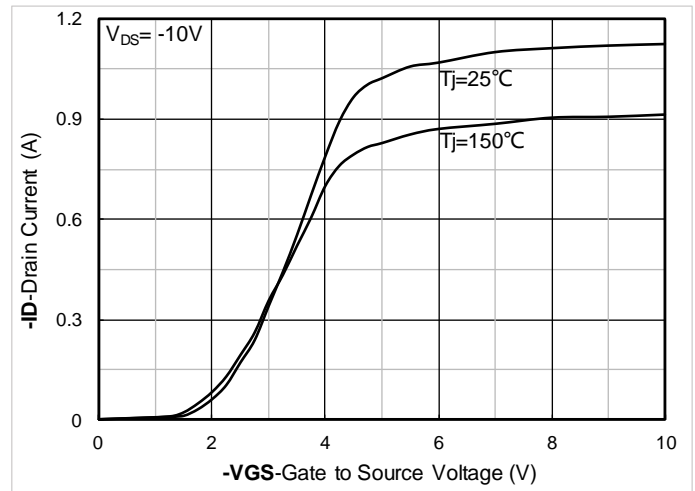


Figure 2. Transfer Characteristics; typical values

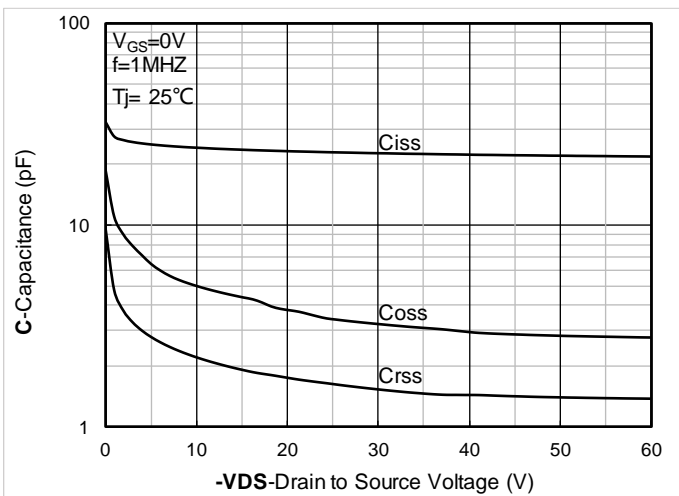


Figure 3. Capacitance Characteristics; typical values

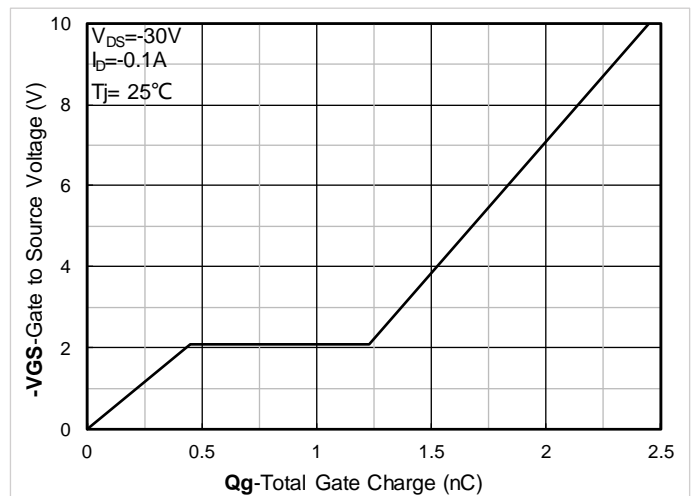


Figure 4. Gate Charge; typical values



YJL8402ADW

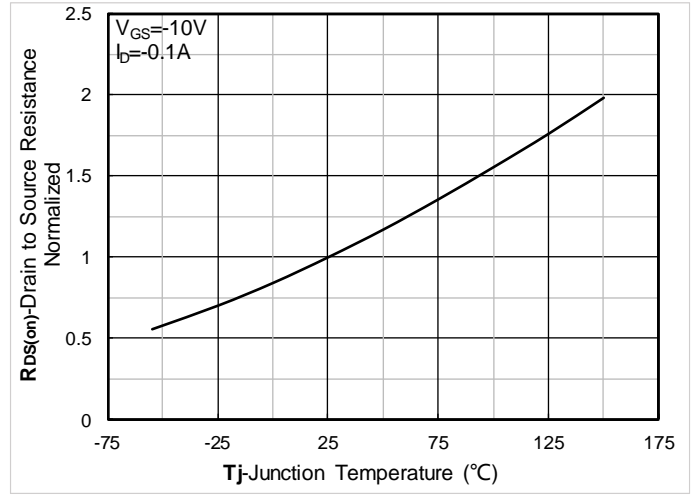
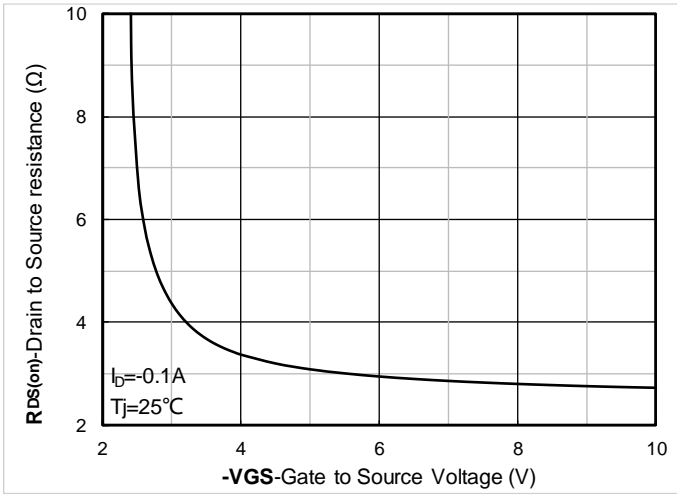


Figure 5. On-Resistance vs. Gate to Source Voltage; typical values

Figure 6. Normalized On-Resistance

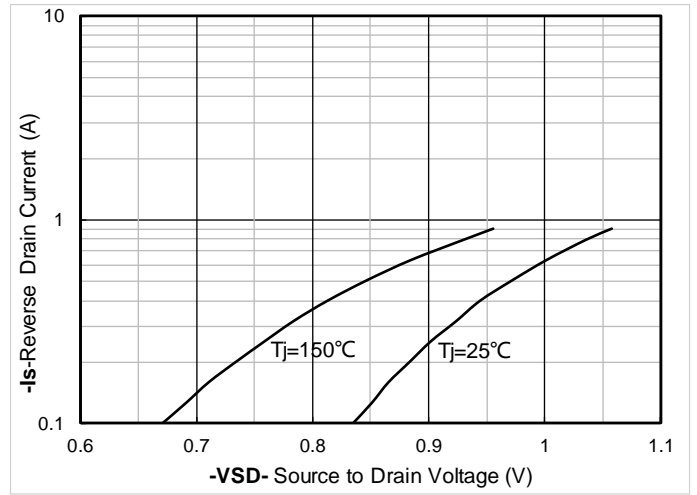
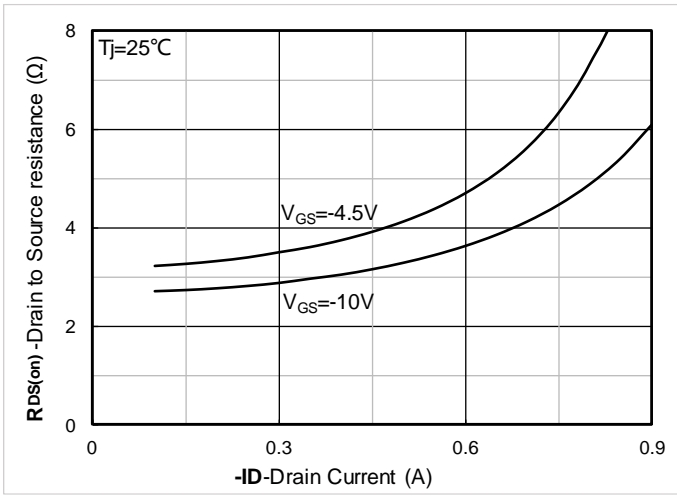


Figure 7. R_DS(on) vs. Drain Current; typical values

Figure 8. Forward characteristics of reverse diode; typical values

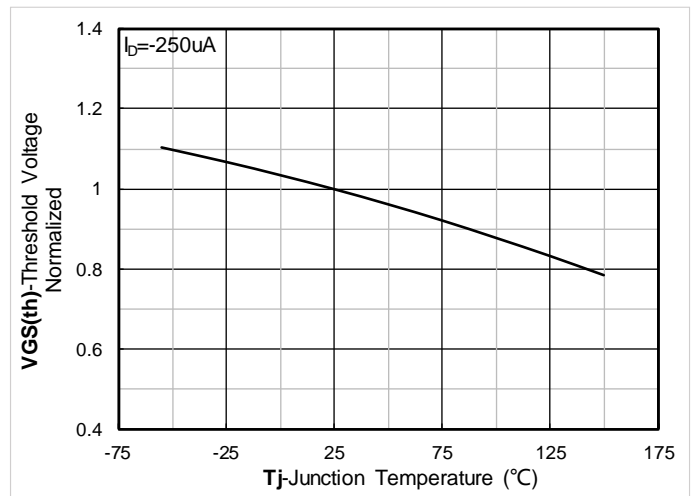
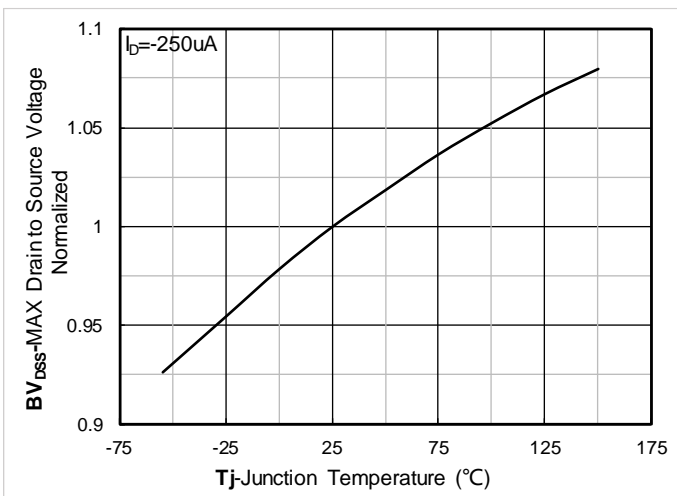


Figure 9. Normalized breakdown voltage

Figure 10. Normalized Threshold voltage



YJL8402ADW

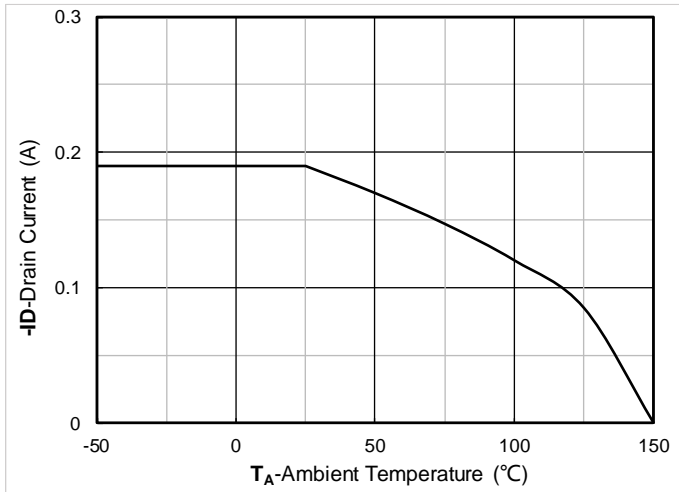


Figure 11. Current dissipation

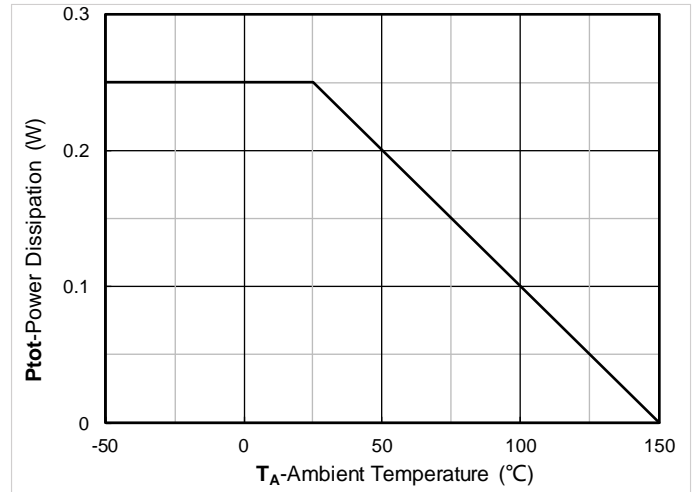


Figure 12. Power dissipation

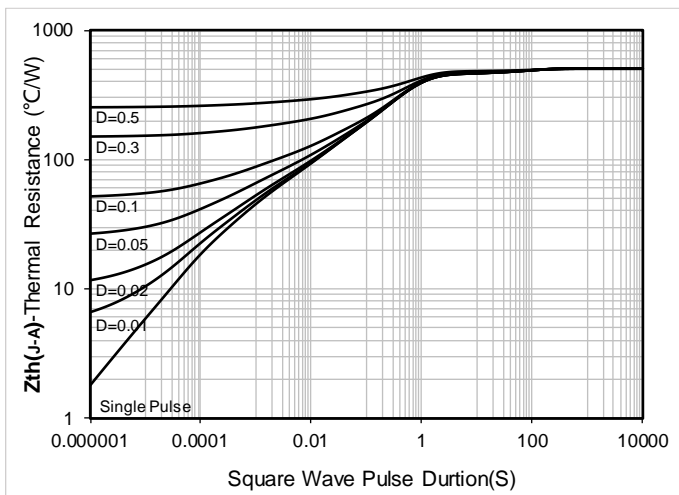


Figure 13. Maximum Transient Thermal Impedance

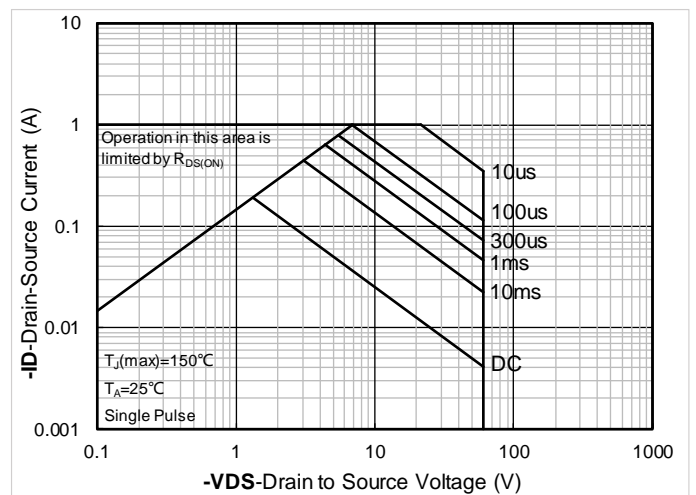
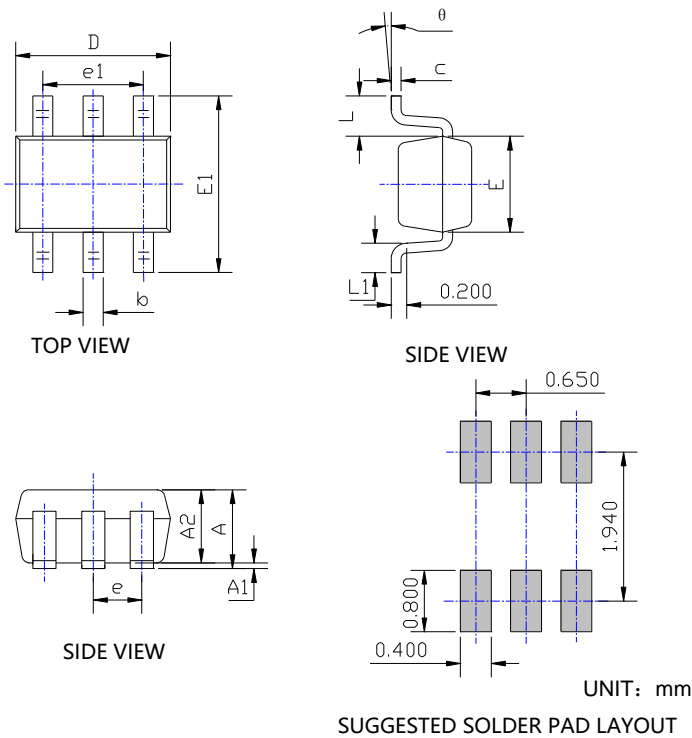


Figure 14. Safe Operation Area

■ SOT-363 Package information



SYMBOL	DIMENSIONS			
	INCHES		Millimeter	
	MIN.	MAX.	MIN.	MAX.
A	0.035	0.043	0.900	1.100
A1	0.000	0.004	0.000	0.100
A2	0.035	0.039	0.900	1.000
b	0.006	0.014	0.150	0.350
c	0.004	0.010	0.100	0.250
D	0.071	0.087	1.800	2.200
E	0.045	0.053	1.150	1.350
E1	0.085	0.096	2.150	2.450
e	0.026TYP		0.650TYP	
e1	0.047	0.055	1.200	1.400
L	0.021REF		0.525REF	
L1	0.010	0.018	0.260	0.460
θ	0°	8°	0°	8°

NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.



YJL8402ADW

Disclaimer

The information presented in this document is for reference only. Yangzhou Yangjie Electronic Technology Co., Ltd. reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel controllers and other safety devices), Yangjie or anyone on its behalf, assumes no responsibility or liability for any damages resulting from such improper use of sale.

This publication supersedes & replaces all information previously supplied. For additional information, please visit our website <http://www.21yangjie.com> , or consult your nearest Yangjie's sales office for further assistance.